

ABSTRACT

(Problem)

5 To provide an IC socket wherein solder crack and warp can be prevented by absorbing the difference of the thermal expansion coefficients of the housing and the board without reducing the strength of the housing.

(Solution)

10 First slits 50a having bottoms and extending from an upper surface toward a lower surface of a housing 20 are formed between predetermined rows of pin contact receiving openings 32 formed in upper surfaces of contact press fit portion receiving holes 31 arranged in a matrix form with the holes penetrating the upper and lower surfaces of the housing 20. And second slits 50b having bottoms and extending from the lower surface
15 toward the lower surface of the housing 20 are formed between predetermined rows of solder ball receiving openings 34 formed in lower surfaces of the contact press fit portion receiving holes 31 at locations where the first slit 50a is not formed.

Fig. 4